

LMH1208 12G UHD-SDI Dual Output Cable Driver

1 Features

- Supports ST-2082-1 (12G), ST-2081-1 (6G), ST-424 (3G), ST-292 (HD), and ST-259 (SD)
- Compatible With DVB-ASI and AES10 (MADI)
- Dual Differential Output Cable Drivers
- On-Chip 75-Ω Termination and Return Loss Compensation Network
- Host-Side Equalized 100-Ω Loop-Back Output
- Programmable Slew Rate Control on 75-Ω Outputs
- Programmable Pre-Emphasis and Output Amplitude on 75-Ω Outputs
- Programmable De-Emphasis and Output Amplitude on 100-Ω Output
- Polarity Inversion on 75-Ω and 100-Ω Outputs
- Automatic Power Save in Absence of Input Signal
 - Power Consumption: 25 mW (Typical)
- Power-Down Control Through ENABLE Pin
- Single 2.5-V Supply
 - Power Consumption: 255 mW (Typical)
- Programmable Through Pins, SPI, or SMBus Interface
- –40°C to +85°C Operating Temperature Range
- 5-mm × 5-mm, 32-pin WQFN Package

2 Applications

- SMPTE Compatible Serial Digital Interface
- UHDTV/4K/8K/HDTV/SDTV Video
- Broadcast Video Routers, Switchers, Distribution Amplifiers, and Monitors
- Digital Video Processing and Editing

3 Description

LMH1208 device is a 12G UHD-SDI low power dual output cable driver. It supports SMPTE video rates up to 11.88 Gbps, enabling UHD video for 4K/8K applications. The additional equalized 100-Ω driver output on the host-side can be used for monitoring or signal distribution purposes.

The programmable PCB input equalizer provides high frequency boost to reduce inter symbol interference (ISI) induced by PCB board trace. The integrated 75-Ω termination and return loss network at both cable driver outputs facilitate overall system design in meeting stringent SMPTE return loss requirements.

Input Signal Detect determines the presence of a valid signal at the input of the cable driver. This sensing feature may be used to alert the user of a system fault and activate a Power Save Mode, reducing the power consumption of the cable driver. The LMH1208 provides selectable slew rates for data rates up to 11.88 Gbps. The output slew rate and amplitude can be controlled by pin, SPI, or SMBus control.

The LMH1208 is powered from a single 2.5-V supply. It is offered in a small footprint 5 mm × 5 mm 32-pin WQFN package. The LMH1208 is pin compatible with the LMH1228 (12G Dual Cable Driver with Integrated Reclocker).

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
LMH1208	WQFN (32)	5.00 mm × 5.00 mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

Simplified Block Diagram

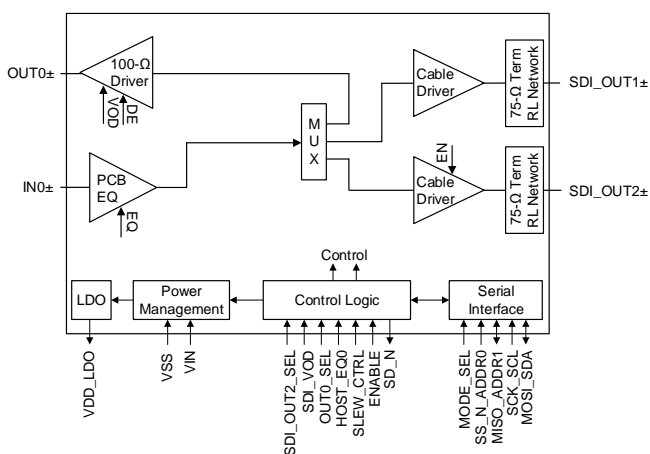


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4 Revision History

DATE	REVISION	NOTES
March 2017	*	Initial release.

5 Device and Documentation Support

5.1 Documentation Support

5.1.1 Related Documentation

For related documentation, see the following:

[QFN/SON PCB Attachment Application Report \(SLUA271\)](#)

5.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

5.3 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

5.4 Trademarks

E2E is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

5.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

5.6 Export Control Notice

Recipient agrees to not knowingly export or re-export, directly or indirectly, any product or technical data (as defined by the U.S., EU, and other Export Administration Regulations) including software, or any controlled product restricted by other applicable national regulations, received from Disclosing party under this Agreement, or any direct product of such technology, to any destination to which such export or re-export is restricted or prohibited by U.S. or other applicable laws, without obtaining prior authorization from U.S. Department of Commerce and other competent Government authorities to the extent required by those laws.

5.7 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

6 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LMH1208RTVR	ACTIVE	WQFN	RTV	32	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	L1208	Samples
LMH1208RTVT	ACTIVE	WQFN	RTV	32	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	-40 to 85	L1208	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LMH1208RTVR	WQFN	RTV	32	1000	180.0	12.4	5.3	5.3	1.1	8.0	12.0	Q2
LMH1208RTVT	WQFN	RTV	32	250	180.0	12.4	5.3	5.3	1.1	8.0	12.0	Q2

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LMH1208RTVR	WQFN	RTV	32	1000	210.0	185.0	35.0
LMH1208RTVT	WQFN	RTV	32	250	210.0	185.0	35.0

THERMAL PAD MECHANICAL DATA

RTV (S-PWQFN-N32)

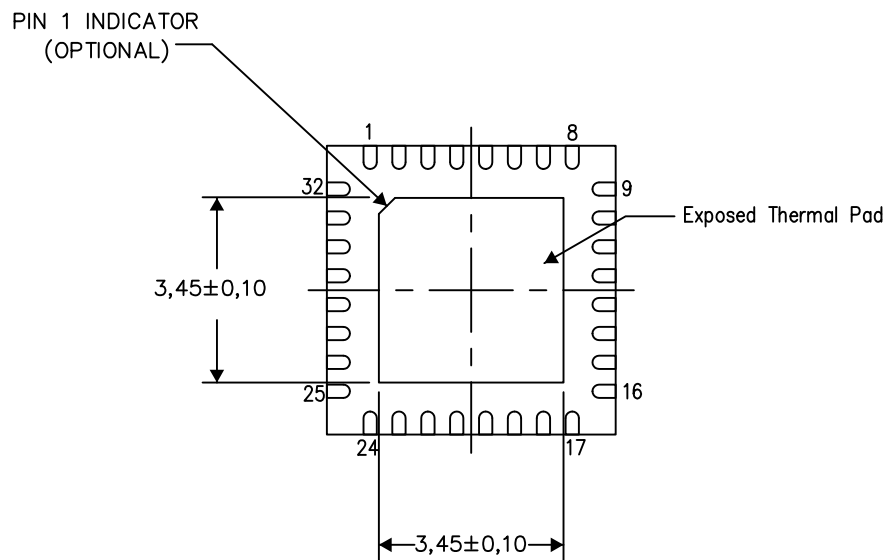
PLASTIC QUAD FLATPACK NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



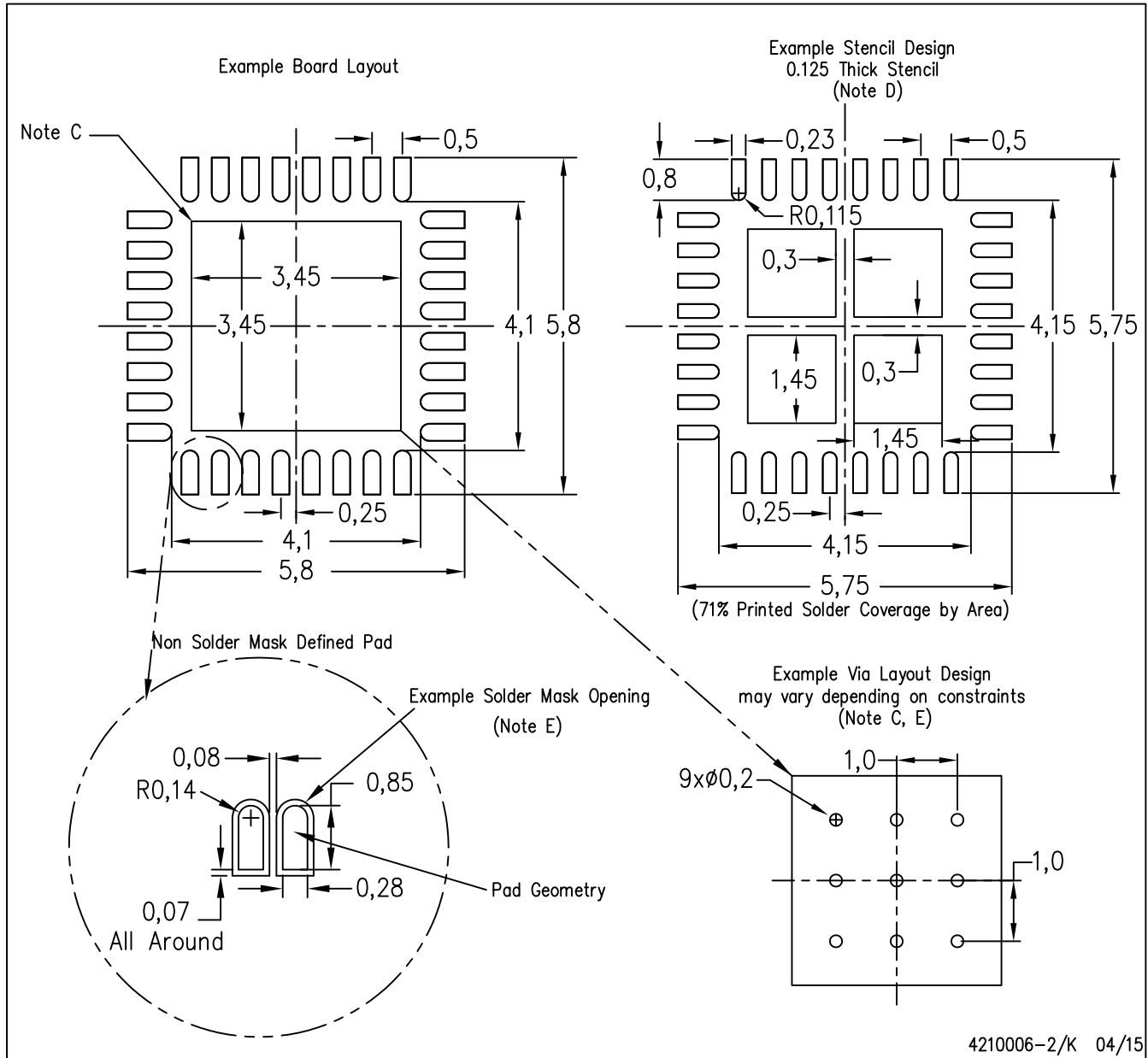
Exposed Thermal Pad Dimensions

4206250-2/Q 05/15

NOTE: All linear dimensions are in millimeters

RTV (S-PWQFN-N32)

PLASTIC QUAD FLATPACK NO-LEAD



4210006-2/K 04/15

- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack Packages, Texas Instruments Literature No. SCBA017, SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - Customers should contact their board fabrication site for recommended solder mask tolerances and via tenting recommendations for vias placed in the thermal pad.

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